

Congress of the United States

Washington, DC 20515

September 25, 2025

Secretary Howard Lutnick
U.S. Department of Commerce
1401 Constitution Avenue, NW
Washington, D.C. 20230

Dear Secretary Lutnick:

We urge the Department of Commerce to ensure the timely and orderly transition of the National Semiconductor Technology Center's (NSTC) programs and funding from the National Center for the Advancement of Semiconductor Technologies (NATCAST) to the National Institute of Standards and Technology (NIST). And we look forward to NIST reaffirming Arizona's selection for the prototyping and packaging facilities.

We commend President Trump and the Department of Commerce for prioritizing America's semiconductor strength, returning manufacturing to the United States, and standing up to the People's Republic of China. The race to design, build, and deploy advanced semiconductors that power artificial intelligence (AI), defense systems, and next-generation technologies is accelerating. China is investing heavily to seize control of this critical industry. America must act with speed and purpose to ensure we win.

Arizona is ready to deliver. The Department of Commerce selected our state to host the co-located NSTC Prototyping Facility and the National Advanced Packaging Manufacturing Program (NAPMP) Advanced Packaging Piloting Facility at Arizona State University's Research Park. With the fastest-growing semiconductor ecosystem in the country, Arizona brings together research, advanced manufacturing, packaging, suppliers, and workforce training in a way no other state can. This facility will bolster the United States' edge against China and allow us to lead the next generation of semiconductor devices. The Advanced Packaging Piloting Facility, in particular, will allow American startups and companies to prototype and package advanced chips domestically, strengthening the supply chain and ensuring American leadership globally.

Arizona hosts the largest advanced packaging facility in the United States and the nation's only advanced 4 nanometer chipmaking technology, with more advanced nodes under construction. And Arizona is the only state in the nation currently building three advanced packaging facilities for leading edge chips. Together, these investments represent billions in private sector investment – presenting a unique opportunity for the Administration to leverage historic industry investment in Arizona to make sure America continues to lead in semiconductors for decade to come.

As this transition proceeds, we encourage the Department to transfer NSTC programs and funds to NIST without delay, and to reaffirm Arizona's selection for the prototyping and packaging facilities. We also believe it is important for Congress and stakeholders to receive a clear

timeline for advancing the Arizona facility, including governance, partner engagement, and construction milestones.

We appreciate the Trump administration's leadership in this effort. Arizona stands ready to partner with you to ensure that the United States, not China, leads the world in semiconductor research, innovation, and manufacturing.

Sincerely,



Andy Biggs
Member of Congress



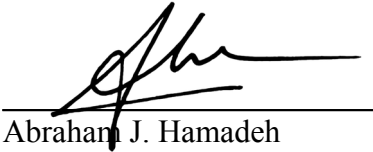
Elijah Crane
Member of Congress



Juan Ciscomani
Member of Congress



Paul A. Gosar, D.D.S.
Member of Congress



Abraham J. Hamadeh
Member of Congress

CC:

Craig Burkhardt, Director of the National Institute of Standards and Technology

Michael Kratsios, Director of Office of Science and Technology Policy

David Sacks, White House AI & Crypto Czar